


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/20/11503	
1.3 Title of PCN	JSCC change WBC to DAF – for UQFN4x4 COL28L & UQFN5x5 COL32L packages for STM8L, STM8T, STM32L, STM32G, STM32F listed products	
1.4 Product Category	STM32F04 32K, STM32F050x 32K STM32F33x 64K, STM32G0 128K, STM32G03 64K, STM32G05 64K STM32G49 512K STM32L020x 16KB, STM32L04x 32K STM8L10x 8K, STM8L15x 32K, STM8L15x 8K, STM8TS50	
1.5 Issue date	2020-12-02	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	GAMERL ANN
2.1.2 Phone	
2.1.3 Email	ann.gamerl@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Die Attach material	JSCC STATSChipPAC (China)

4. Description of change

	Old	New
4.1 Description	Current Die Attach material: - Wafer Backside Coating (WBC) Epoxy Henkel 8006NS	New die attach material: - Die Attach Film (DAF) Hitachi HR5104
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No impact on Form Fit Function	

5. Reason / motivation for change

5.1 Motivation	To multiply the source to reduce line down risk Improve quality. Increase TSSOP20L loading.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	tracability ensured by ST internal tools
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7. Timing / schedule

7.1 Date of qualification results	2020-11-02
7.2 Intended start of delivery	2021-02-18
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	11503 MDG-MCD RER1911 V1.0 PCN11503-UQFN4x4_5x5 COL- WBC to DAF change- reliability evaluation report.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2020-12-02
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9. Attachments (additional documentations)

11503 Public product.pdf
 11503 MDG-MCD RER1911 V1.0 PCN11503-UQFN4x4_5x5 COL- WBC to DAF change- reliability evaluation report.pdf
 11503 PCN11503_Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM8L151G6U6TR	

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